

Description

21-340B is a soft, single part, high thermal conductivity silicone putty thermal gap filler in which no cure is required. This gap filler is designed to be used where large gap tolerances are present and low mechanical stress on delicate components are needed. It is ideal for filling variable gaps between multiple components and a common heat sink.

Specialized rheology allows for easy flow under pressure.



Benefits

- Soft and Compliant Transferring Little To No Pressure Between Interfaces
- Thermal Conductivity: 3.5 W/m-K
- Easily Dispensable
- Fully-Cured (Never Dry)
- Electrically Isolating
- Low Thermal Resistance

Applications

- Cooling components to chassis, frame, or other mating components
- Home & Small Office Network
- Mass Storage Devices
- Automotive Electronics
- Telecommunication Hardware
- Radios
- LED Solid State Lighting
- Power Electronics
- Set Top Boxes
- Audio & Video Component

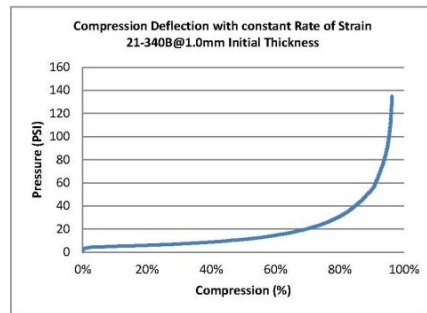
Disclaimers

- The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the issuing date of this TDS. When using our products, no matter what type of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this TDS are subject to change without prior notice.
- Do not use the products beyond the specifications described in this TDS. This TDS explains the typical performance of the products as individual component. Before use, check and evaluate their operations when installed in your products.
- Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other significant damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/gas equipment, rotating equipment, and disaster/crime prevention equipment.

Typical Properties

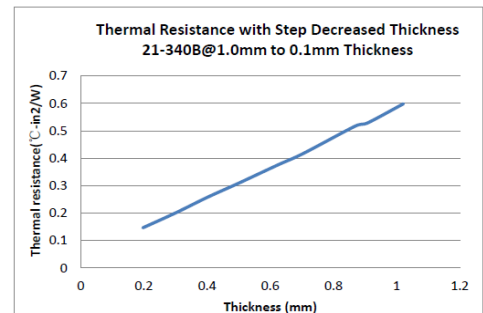
Properties	21-340B	Test Method	
Thermal	Thermal Conductivity (W/m-K)	3.5	
	Continuous Use Temp. (°C)	-55~150	
Physical	Color	Green	
	Density (g/cc)	3.2	
	Flow Rate (g/min)	26	55cc syringe barrel, φ2.4mm needle@ 90psi
		48	180cc syringe barrel, φ 3mm needle@ 90psi
Electrical	Typical Minimum Bondline Thickness (mm)	0.1	Jones
	Dielectric Strength (KV/mm)	>5	ASTM D149
	Volume Resistivity (ohm-cm)	10 ¹³	ASTM D257
Regulatory	Dielectric Constant @1MHz	4.85	ASTM D150
	Flammability Rating	V0	UL 94
	Self Life @25°C (Months)	18	JONES
	RoHS Compliant	YES	-

Compression Deflection



21-340B Thermal Gel 1.0mm initial thick; 1 inch² test sample;
Rate of strain = 1.0 mm/min

Thermal Resistance



*Specimen Area: 1inch²
The thickness of sample is controlled by limit slice
Decreased Thickness step = 0.1mm

Standard Package

21-340B-001-050M=Thermal Gel 21-340B in a 50cc cartridge (150g)
21-340B-001-180M=Thermal Gel 21-340B in a 180cc cartridge (500g)
21-340B-001-300M=Thermal Gel 21-340B in a 300cc cartridge (800g)
21-340B-001-001G=Thermal Gel 21-340B in a 1 Gallon pail (8~13Kg)
21-340B-001-005G=Thermal Gel 21-340B in a 5 Gallon pail (25Kg)

Storage Requirement

Room Temperature Between 8 to 30 degree
R.H. 50%

* Unopened Original Package

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